

# Low Capacitance ESD Protection for High-Speed Serial Interfaces

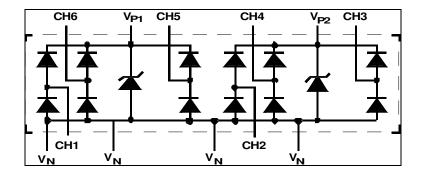
CM1263-06DE

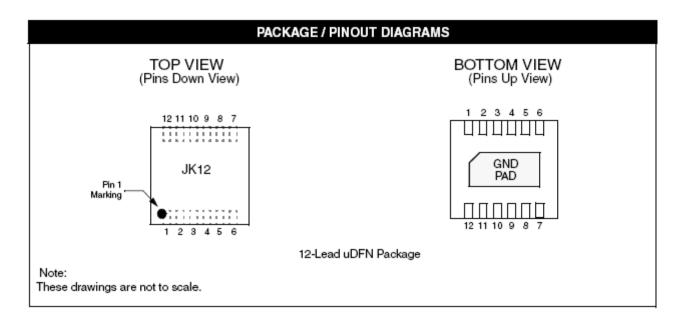
#### **Features**

- 6 channels of ESD Protection
- 1pF loading capacitance per channel typical
- ±8kV ESD protection (IEC 61000-4-2, contact discharge)
- ±15kV ESD protection (IEC 61000-4-2, air discharge)
- RoHS-compliant uDFN-12 package

## **Applications**

- LCD and Camera data lines in wireless handsets that use high-speed serial interfaces such as MDDI, MIPI, MVI and MPL
- I/O port protection for mobile handsets, notebook computers, PDAs etc.
- · Wireless handsets
- Handheld PCs/PDAs
- LCD and camera modules





PIN DESCRIPTIONS							
Pin	DESCRIPTION	Pin	DESCRIPTION				
1	V <sub>N</sub> *	7	(CH3) ESD Channel #3				
2	(CH1) ESD Channel #1	8	V <sub>P2</sub> for Channels 2, 3, and 4				
3	V <sub>N</sub> *	9	(CH4) ESD Channel #4				
4	V <sub>N</sub> *	10	(CH5) ESD Channel #5				
5	(CH2) ESD Channel #2	11	$V_{p_1}$ for Channels1, 5, and 6				
6	V <sub>N</sub> *	12	(CH6) ESD Channel #6				
		DAP*	Backside, GND Pad, V <sub>N</sub> *				

Note 1: \* To achieve best ESD performance, all  $V_{\scriptscriptstyle N}$  pins must be connected.

# CM1263-06DE

## **Ordering Information**

PART NUMBERING INFORMATION						
PIN	PACKAGE	LEAD-FREE FINISH	Part Marking			
12	uDFN	CM1263-06DE	JK12			

Note 1: Parts are shipped in Tape and Reel form unless otherwise specified.

## **Specifications**

ABSOLUTE MAXIMUM RATINGS					
PARAMETER	RATING	UNITS			
Operating Supply Voltage (V <sub>P</sub> - V <sub>N</sub> )	6.0	V			
Operating Temperature Range	-40 to +85	∞			
Storage Temperature Range	-65 to +150	℃			
DC Voltage at any channel input	$(V_{_{\rm N}}$ - 0.5) to $(V_{_{\rm P}}$ + 0.5)	V			

	ELECTRICAL OPERATING CHARACTERISTICS (SEE NOTE 1)									
SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS				
V <sub>P</sub>	Operating Supply Voltage (V <sub>P</sub> -V <sub>N</sub> )			3.3	5.5	V				
I <sub>P</sub>	Operating Supply Current	$V_P=3.3V$ , $V_N=0V$ (per $V_P$ pin)			8.0	μΑ				
V <sub>F</sub>	Diode Forward Voltage Top Diode Bottom Diode	$T_A=25$ °C; $I_F=8$ mA; $V_P=3.3$ V, $V_N=0$ V	0.60 0.60	0.80 0.80	0.95 0.95	V V				
I <sub>LEAK</sub>	Channel Leakage Current	T <sub>A</sub> =25 °C; V <sub>P</sub> =3.3V, V <sub>N</sub> =0V (Channel 1)			250	nA				
		V <sub>P</sub> =3.3V, V <sub>N</sub> =0V (Channels 1-6);			1000	nA				
I <sub>R</sub> Reverse (Leakage Current)		V <sub>P</sub> =floating; V <sub>N</sub> =0V (per channel)			1000	nA				
C <sub>IN</sub>	Channel Input Capacitance	el Input Capacitance At 1 MHz, $V_p=3.3V$ , $V_N=0V$ , $V_{IN}=0V$		0.88	1.2	pF				
$\Delta C_{IN}$	Channel Input Capacitance Matching	At 1 MHz, $V_P = 3.3V$ , $V_N = 0V$ , $V_{IN} = 0V$		0.02		pF				
C <sub>MUTUAL</sub>	Mutual Capacitance between signal pin and adjacent signal pin	At 1 MHz, $V_P = 3.3V$ , $V_N = 0V$ , $V_{IN} = 0V$		0.11		pF				
V <sub>ESD</sub>	ESD Protection Peak Discharge Voltage at any channel input, in system a) Contact discharge per IEC 61000-4-2 standard b) Air discharge per IEC 61000-4-2 standard	Notes 2 and 3; T <sub>A</sub> =25 ℃	±8 ±15			kV kV				
V <sub>CL</sub>	Channel Clamp Voltage Positive Transients Negative Transients	$T_A = 25 ^{\circ}\text{C}$ , $I_{PP} = 1 ^{\circ}\text{A}$ , $t_P = 8/20 ^{\circ}\text{\mu S}$ ; Notes 3		+9.96 -1.6		<b>V V</b>				
R <sub>DYN</sub>	Dynamic Resistance Positive Transients Negative Transients	$T_A$ =25 °C, $I_{pp}$ = 1A, $t_p$ = 8/20 $\mu$ S Any I/O pin to Ground; Note 3		0.96 0.5		Ω Ω				

Note 1: All parameters specified at  $T_{_A} = -40\,^{\circ}\text{C}$  to +85ûC unless otherwise noted. Note 2: Standard IEC 61000-4-2 with  $C_{_{Discharge}} = 150 \text{pF}, \ R_{_{Discharge}} = 330\Omega, \ V_{_P} = 3.3 \text{V}, \ V_{_N} \ \text{grounded}.$  Note 3: These measurements performed with no external capacitor on  $V_{_P}(V_{_P} \text{floating})$ .

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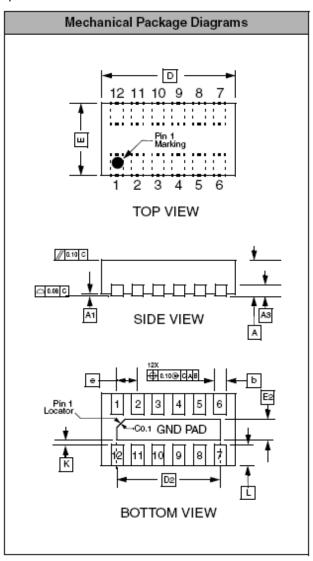
#### **Mechanical Details**

#### uDFN-12 Mechanical Specifications, 0.4mm

Dimensions for the 12-lead, 0.4mm pitch uDFN pack- age are presented below.

PACKAGE DIMENSIONS							
Package	uDFN MO-229C <sup>*</sup>						
JEDEC No.							
Leads			1	12			
Dim.	Millimeters			Inches			
5	Min	Nom	Max	Min	Nom	Max	
Α	0.45	0.50	0.55	0.018	0.020	0.022	
<b>A</b> 1	0.00	0.02	0.05	0.000	0.001	0.002	
А3	0.127 REF 0.005 RE			.005 RE	F		
b	0.15	0.20	0.25	0.006 0.008		0.010	
D	2.40	2.50	2.60	0.094	0.098	0.102	
D2	1.90	2.00	2.10	0.075	0.079	0.083 0.057	
E	1.25	1.35	1.45	0.049	0.053		
E2	0.30	0.40	0.50	0.012 0.016		0.020	
е	0.40 BSC			0.016 BSC			
К	0.22 REF			0.0087 REF			
L	0.15	0.25	0.35	0.006	0.010	0.014	
# per tape and reel	3000 pieces						
	Contro	olling din	nension:	millimet	ers		

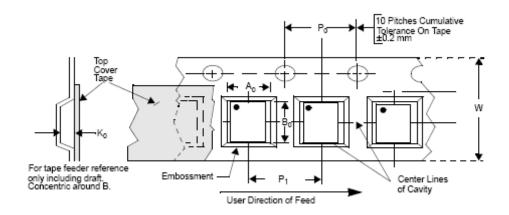
<sup>\*</sup>This package is compliant with JEDEC standard MO-229C with the exception of the D, D2, E, E2, K and L dimensions as called out in the table above.



Dimensions for 12-Lead, 0.4mm Pitch uDFN Package

#### **Tape and Reel Specifications**

PART NUMBER	PACKAGE SIZE (mm)	POCKET SIZE (mm) B <sub>o</sub> X A <sub>o</sub> X K <sub>o</sub>	TAPE WIDTH W	REEL DIAMETER	QTY PER REEL	P <sub>o</sub>	P <sub>1</sub>
CM1263-06DE	2.50 X 1.35 X 0.50	2.75 X 1.60 X 0.60	8mm	178mm (7")	3000	4mm	4mm



## CM1263-06DE

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